

SEMICONDUCTOR PACKAGES AND METHODS OF PACKAGING

SEMICONDUCTOR DEVICES

ABSTRACT

Semiconductor packages and methods of forming a semiconductor package are disclosed. The method includes providing at least one die having first and second surfaces. The second surface of the die includes a plurality of conductive pads. A support carrier is provided and the at least one die is attached to the support carrier. The first surface of the at least one die is facing the support carrier. A cap having first and second surfaces is formed to encapsulate the at least one die. The second surface of the cap is disposed at a different plane than the second surface of the die.

Fig. 1a